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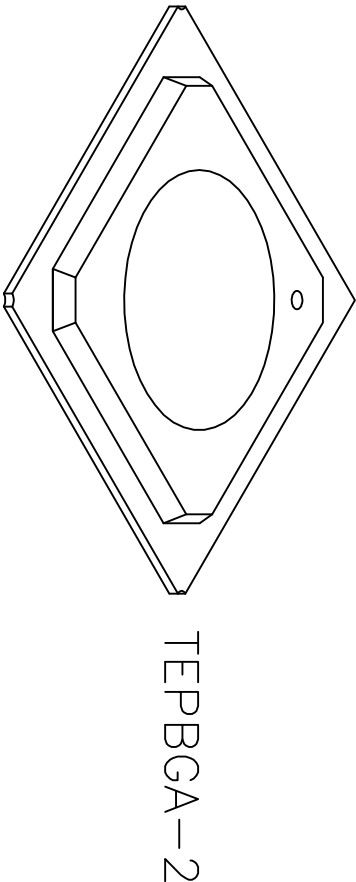
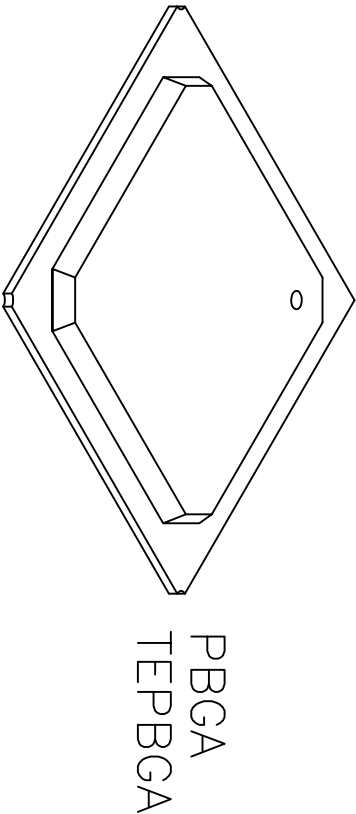
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REVISION HISTORY							
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GERBER FILE NAME	INCORPORATOR	DATE
02	C05707	CHANGED CAP TOLERANCE	MWALT	N/A	N/A	MWALT	03/23/99
03	C06663	ADDED 233 BALL COUNT	GREME	N/A	N/A	GREME	08/17/99
04	C09629	ADDED 177 BALL COUNT	GREME	N/A	N/A	PGONZ	07/14/00
05	C13234	REVISED TO JEDEC MS-034	JTURN	N/A	N/A	DARNO	08/28/01
06	C14116	ADDED TEPBGA-2 PACKAGE ADDED 208, 217, 240 AND 249 MATRIX	DARNO	N/A	N/A	DARNO	11/08/01
07	C20673	REMOVED CENTER BALL FROM 192 BALL	SMKANG	N/A	N/A	SMKANG	12/16/02
08	N/A	REVISED THICKNESS SCHEDULE ON SHEET 2	DLADI	N/A	N/A	DLADI	04/14/05



8. REFERENCE SPECIFICATIONS:

- A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0519-2062: MARKING.
C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A, VARIATION BAJ-2.



4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 289.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 17 X 17.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.27mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		Anchor Technology, Inc. Chandler, Arizona, USA Anam Semiconductor, Inc., Seoul, Korea Anchor Technology Philippines, Inc. Manila, Philippines			
DECIMAL X.X ±0.1 X.XX ±0.05 X.XXX ±0.030	ANGULAR ±1°	APPROVALS	DATE	TITLE PACKAGE OUTLINE - PBGA CUSTOM, 17 X 17 MATRIX 23.00mm X 23.00mm, 19.50mm X 19.50mm X 1.17mm MOLD CAP, 1.27mm PITCH, LAMINATE SUBSTRATE, AWW			
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994		DESIGNED A. COPIA	08/15/97	SIZE A3	SID NUMBER	DWG NUMBER	REV
MATERIAL N/A		CHECKED D. ARNOLD	08/15/97	STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
FINISH N/A		PRODUCT MANAGER B. GOGUE	08/15/97	N/A	N/A	NONE	1 OF 7
DO NOT SCALE DRAWING		RELEASED Y.M. KANG	11/18/97				

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